MeshConnect™ EM35x Mini Modules

ZICM35xSP0 and ZICM35xSP2

Ember™ EM35x Transceiver-Based Modules

Integrated Transceiver Modules for ZigBee®/IEEE 802.15.4

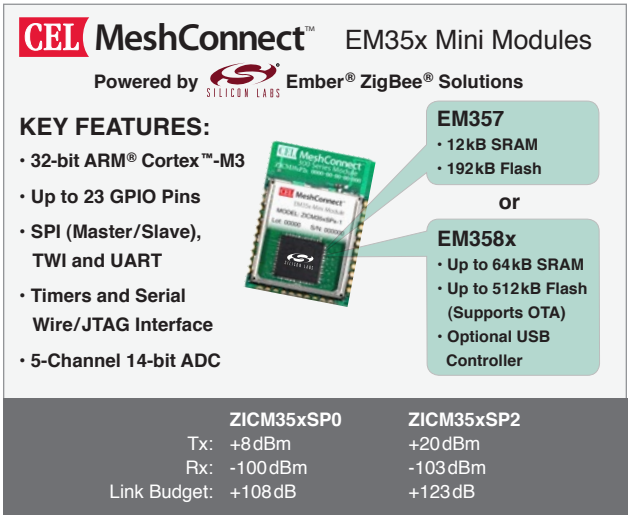
Development Kit Available: ZICM-EM35X-DEV-KIT-3

DESCRIPTION

The MeshConnect™ EM35x Mini Modules from California Eastern Laboratories (CEL) combine high performance RF solutions with the market's premier ZigBee® stack. Available in low and high output power options (+8dBm and +20dBm), these modules can accommodate variable range and performance requirements. The tiny module footprint makes them suitable for a wide range of ZigBee applications. The MeshConnect EM35x Mini Modules are certified and qualified, enabling customers to accelerate time to market by greatly reducing the design and certification phases of development.

CEL's MeshConnect EM35x Mini Modules (ZICM35xSP0 and ZICM35xSP2) are based on the Ember EM35x (EM357 and EM358x) ZigBee compliant System on Chip (SoC) radio ICs. Each IC is a complete single-chip solution, compliant with ZigBee specifications and IEEE 802.15.4.

CEL's EM358x-based Mini Modules (ZICM358xSP0 and ZICM358xSP2) are ideal for customers requiring Over-the-Air (OTA) programming (such as Smart Energy or Home Automation) or a larger memory footprint for complex application control. They also feature an optional on-board Universal Serial Bus (USB) 2.0 full-speed peripheral.



ADDITIONAL FEATURES

- **Data Rate: 250kbps**
- **Advanced Power Management**
- **16 RF Channels**
- **Industry's Premier ZigBee PRO Stack: EmberZNet PRO™**
- **Mini Footprint:**
  - 0.940" x 0.655" (23.9mm x 16.6mm)
- **Antenna Options:**
  1) Integrated PCB Trace Antenna
  2) RF Port for External Antenna
- **Supports Mesh Networks**
- **AES Encryption**
- **FCC, CE and IC Certifications**
- **RoHS Compliant**

APPLICATIONS

- **Smart Energy/Grid Markets**
  - Thermostats
  - In-Home Displays
  - Smart Plugs
- **Home Automation and Control**
  - Energy Management
  - Security Devices
  - HVAC Control
- **Building Automation and Control**
- **Commercial and Residential Lighting**
  - Fixtures and Control
- **Solar Inverters and Control**
- **General ZigBee Wireless Sensor Networking**

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ORDERING INFORMATION

Part Number	Order Number	Description	Min/ Multiple
MeshConnect EM35x Mini Modules	ZICM357SP0-1	EM357 IC, +8dBm output power, PCB trace antenna; Tray Package	330/330
	ZICM357SP0-1-R	EM357 IC, +8dBm output power, PCB trace antenna; Tape and Reel Package	600/600
	ZICM357SP0-1C	EM357 IC, +8dBm output power with castellation pin for external antenna; Tray Package	330/330
	ZICM357SP0-1C-R	EM357 IC, +8dBm output power with castellation pin for external antenna; Tape and Reel Package	600/600
	ZICM357SP2-1	EM357 IC, +20dBm output power, PCB trace antenna; Tray Package	330/330
	ZICM357SP2-1-R	EM357 IC, +20dBm output power, PCB trace antenna; Tape and Reel Package	600/600
	ZICM357SP2-1C	EM357 IC, +20dBm output power with castellation pin for external antenna; Tray Package	330/330
	ZICM357SP2-1C-R	EM357 IC, +20dBm output power with castellation pin for external antenna; Tape and Reel Package	600/600
	ZICM357SP2-2	EM357 IC, +20dBm output power, PCB trace antenna; Tray Package	330/330
	ZICM357SP2-2-R	EM357 IC, +20dBm output power, PCB trace antenna; Tape and Reel Package	600/600
	ZICM357SP2-2C	EM357 IC, +20dBm output power with castellation pin for external antenna; Tray Package	330/330
	ZICM357SP2-2C-R	EM357 IC, +20dBm output power with castellation pin for external antenna; Tape and Reel Package	600/600
	ZICM3588SP0-1	EM3588 IC, +8dBm output power, PCB trace antenna; Tray Package	330/330
	ZICM3588SP0-1-R	EM3588 IC, +8dBm output power, PCB trace antenna; Tape and Reel Package	600/600
	ZICM3588SP0-1C	EM3588 IC, +8dBm output power with castellation pin for external antenna; Tray Package	330/330
	ZICM3588SP0-1C-R	EM3588 IC, +8dBm output power with castellation pin for external antenna; Tape and Reel Package	600/600
	ZICM3588SP2-1	EM3588 IC, +20dBm output power, PCB trace antenna; Tray Package	330/330
	ZICM3588SP2-1-R	EM3588 IC, +20dBm output power, PCB trace antenna; Tape and Reel Package	600/600
	ZICM3588SP2-1C	EM3588 IC, +20dBm output power with castellation pin for external antenna; Tray Package	330/330
	ZICM3588SP2-1C-R	EM3588 IC, +20dBm output power with castellation pin for external antenna; Tape and Reel Package	600/600
MeshConnect EM35x Development Kit	ZICM-EM35X-DEV-KIT-3	MeshConnect EM35x Ember Companion Kit for Ember EM35x Development Kit	1/1

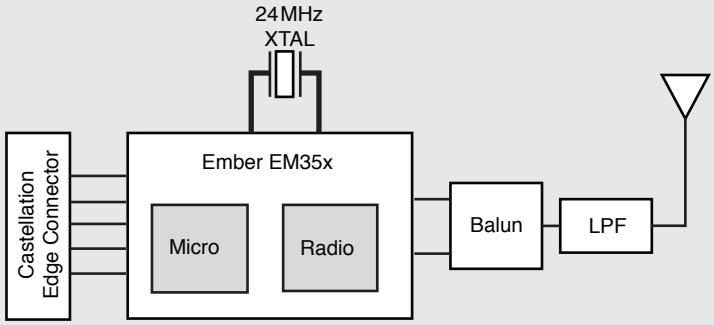
Note: *All packages come in Trays unless a part number has a "-R" designation; part numbers with the "-R" indicate a Tape and Reel Package Option.*

ZICM35xSPx PRODUCT COMPARISON TABLE

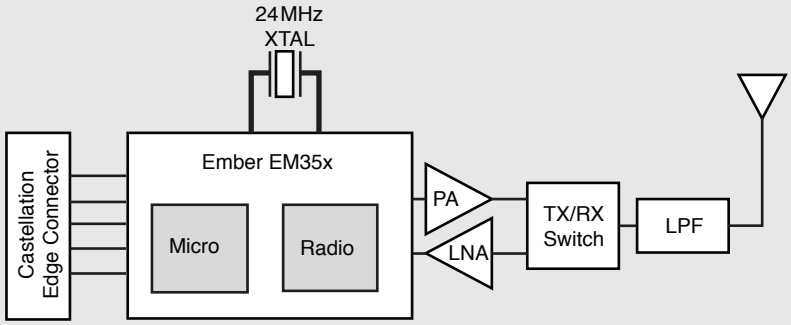
Order Number	MCU				Performance					Comments
	Flash Memory	SRAM Memory	USB	I/O	Tx Power Output	Rx Sensitivity	Rx Current	Tx Current	Sleep / Suspend Current	
					dBm	dBm	mA	mA	µA	
ZICM357SP0-1 ZICM357SP0-1C	192 kB	12 kB	–	23	+8	-100	30	44	1	
ZICM357SP2-1 ZICM357SP2-1C				22	+20	-103	34	150		
ZICM357SP2-2 ZICM357SP2-2C				21						Reduced GPIO allows for faster 'time to sleep' state
ZICM3588SP0-1 ZICM3588SP0-1C	512 kB	64 kB	✓	23	+8	-100	30	44	2.4	2.4 µA with entire RAM retained. Lower sleep current can be achieved by retaining less RAM
ZICM3588SP2-1 ZICM3588SP2-1C				21	+20	-103	34	150		

MODULE BOCK DIAGRAMS

EM35x Mini Module (ZICM35xSP0)



EM35x Mini Module (ZICM35xSP2)



DEVELOPMENT TOOLS

Ember Companion Kit

CEL's MeshConnect EM35x Ember Companion Kit is designed to work with the Silicon Laboratories/ Ember Development Kits (EM35X-DEV and EM35X-DEV-IAR). Each module in the CEL Development Kit is soldered on a carrier board making it pin-for-pin compatible with the Ember Development Board.

Mini Modules Programming Fixture

CEL's MeshConnect EM35x Mini Modules Programming Fixture is a programming assembly designed to be used with the CEL ZICM35xSPx MeshConnect Mini Modules. It is useful for production programming or during application development when multiple firmware images are required to be loaded into a CEL Mini Module for testing and debugging. The programming assembly must be used in conjunction with an Ember Debug/InSight Adapter (ISA3) from Silicon Labs.

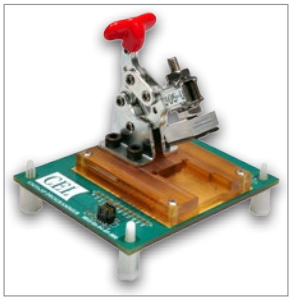
For more information regarding the MeshConnect Development Tools, refer to the respective documents, or visit www.cel.com/MeshConnect.

EM35x Ember Companion Kit

Kit Contents:

- **ZICM357SP0-1C-SL**
- **ZICM357SP2-1-SL**
- **ZICM357SP2-1C-SL**
- **ZICM3588SP0-1C-SL**
- **ZICM3588SP2-1-SL**
- **ZICM3588SP2-1C-SL**

EM35x Programming Fixture



DEVELOPMENT TOOLS ORDERING INFORMATION

Part Number	Order Number	Description
MeshConnect EM35x Ember Companion Kit	**ZICM-EM35X-DEV-KIT-3**	MeshConnect EM35x Ember Companion Kit for Silicon Laboratories/ Ember EM35x Development Kit
MeshConnect EM35x Programming Fixture	**ZICM35xSPx-PF-1**	MeshConnect EM35x Mini Modules (ZICM35xSPx) Programming Fixture

TRANSCEIVER IC

CEL's MeshConnect EM35x Mini Modules use the Ember EM35x transceiver (EM357 or EM358x) IC. The IC incorporates a RF transceiver with baseband modem, a hardwired MAC and an embedded ARM® Cortex™-M3 microcontroller, offering an excellent low cost, high performance solution for all IEEE 802.15.4/ZigBee applications. For more information about the EM35x IC, visit www.silabs.com.

ANTENNA

CEL's MeshConnect EM35x Mini Modules include an integrated Printed Circuit Board (PCB) trace antenna. An optional configuration which uses a castellation pin on the module allows the user to connect an external antenna. The ZICM35xSP0 has been certified with the PCB trace antenna only while the ZICM35xSP2 has been certified with the PCB trace antenna and a Nearson half-wave dipole antenna (part number: S181AH-2450S) on a 4 inch cable using the castellation pin of the module. Please refer to the document *ZICM35xSP2-1C External Antenna Implementation* for details describing the requirements that must be followed to take advantage of the CEL certification. See Ordering Information on Page 3.

The PCB antenna employs a topology that is compact and highly efficient. To maximize range, an adequate ground plane must be provided on the host PCB. Correctly positioned, the ground plane on the host PCB will contribute significantly to the antenna performance (it should not be directly under the module PCB Antenna). The position of the module on the host board and overall design of the product enclosure contribute to antenna performance. Poor design affects radiation patterns and can result in reflection, diffraction and/or scattering of the transmitted signal.

For optimum antenna performance, the MeshConnect Modules should be mounted with the PCB trace antenna overhanging the edge of the host board. To further improve performance, a ground plane may be placed on the host board under the module, up to the antenna (a minimum of 1.5" x 1.5" is recommended). The installation of an uninterrupted ground plane on a layer directly beneath the module will also allow you to run traces under this layer. CEL can provide assistance with your PCB layout.

The following are some design guidelines to help ensure antenna performance:

- Never place the ground plane or route copper traces directly underneath the antenna portion of the module
- Never place the antenna close to metallic objects
- In the overall design, ensure that wiring and other components are not placed near the antenna
- Do not place the antenna in a metallic or metalized plastic enclosure
- Keep plastic enclosures 1cm or more away from the antenna in any direction

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante.

POWER AMPLIFIER

CEL's MeshConnect EM35x High Power Mini Module (ZICM35xSP2) includes a Power Amplifier (PA). This PA delivers high efficiency, high gain and high output power (P_{out} = +20.0dBm typical) to provide an extended range and reliable transmission for fewer nodes in a network. For the ZICM35xSP2, Power Mode 2 with Power Setting -2 is the maximum setting allowed for FCC Compliance. Operating in Power Mode 3 at higher power settings may damage the PA.

USB

The ZICM358xSPx-1 Modules have an integrated USB 2.0-compliant, full-speed (12Mbps) device peripheral. For more information, refer to the *EM35x SoC Datasheet* link provided in the References Section of this document.

SOFTWARE/FIRMWARE

CEL's MeshConnect EM35x Mini Modules are ideal platforms for EmberZNet PRO, the industry's most deployed and field proven ZigBee compliant stack supporting the ZigBee PRO feature set. EmberZNet PRO is a complete ZigBee protocol software package containing all the elements required for mesh networking applications. For more information regarding the software development for this IC, visit www.silabs.com.

CEL provides reference software that runs multiple functions and executes various commands. For example, users can set up a simple ZigBee network to perform Range and Packet Error Rate (PER) tests between two devices. This allows the user to evaluate the module's RF performance in their own environment. The software can also place the module in various operating modes which allows for testing of low-level RF performance, GPIO functionality, etc.

The ZICM35xSP0 Module uses the transceiver's primary RF ports for transmitting and should use Power Mode 1 (EMBER_TX_POWER_MODE_BOOST in the EmberZNet API).

The ZICM35xSP2 Module uses the transceiver's alternate RF ports for transmitting and should use Power Mode 2 (EMBER_TX_POWER_MODE_ALTERNATE in the EmberZNet API). GPIO PC5 must also be configured as ALT_OUT (push/pull).

ABSOLUTE MAXIMUM RATINGS

Description		MeshConnect ZICM35xSPx Module		Unit
		Min	Max	
Power Supply Voltage (V_{DD})		-0.3	3.6	VDC
Voltage on any I/O Line		-0.3	V_{DD} + 0.3	VDC
RF Input Power	ZICM35xSP0	–	+15	dBm
	ZICM35xSP2	–	+5	
Storage Temperature Range		-40	125	°C
Reflow Soldering Temperature		–	260	°C

Note: *Exceeding the maximum ratings may cause permanent damage to the module or devices.*

RECOMMENDED OPERATING CONDITIONS

Description	MeshConnect ZICM35xSPx Module			Unit
	Min	Typ	Max	
Power Supply Voltage (V_{DD})	2.1	3.3	3.6	VDC
Input Frequency	2405	–	2480	MHz
Ambient Temperature Range	-40	25	85	°C

DC CHARACTERISTICS *(@ 25°C, V_{DD} = 3.3V, ZICM35xSP0 TX Power Mode 1, ZICM35xSP2 TX Power Mode 2)*

Description		MeshConnect ZICM35xSPx Module			Unit
		Min	Typ	Max	
Transmit Mode Current @ +8dBm	ZICM35xSP0	–	44	–	mA
Transmit Mode Current @ 0dBm		–	31	–	mA
Receive Mode Current		–	30	–	mA
Transmit Mode Current @ +20dBm	ZICM35xSP2	–	150	–	mA
Transmit Mode Current @ 0dBm		–	58	–	mA
Receive Mode Current		–	34	–	mA
Sleep Mode Current	ZICM357SPx	–	1	–	µA
Sleep Mode Current	ZICM358xSPx	–	2.4*	–	µA

***Note:** The increased sleep current on the ZICM358xSPx is at 3.6VDC with all the RAM retained. Lower sleep currents can be achieved if less RAM is retained during sleep.*

RF CHARACTERISTICS *(@ 25°C, V_{DD} = 3.3 V, ZICM35xSP0 TX Power Mode 1, ZICM35xSP2 TX Power Mode 2)*

Description		MeshConnect ZICM35xSPx Module			Unit
		Min	Typ	Max	
General Characteristics					
RF Frequency Range		2405	–	2480	MHz
RF Channels		11	–	26	–
Frequency Error Tolerance		-96.2	–	96.2	kHz
Transmitter					
Maximum Output Power	ZICM35xSP0	–	+8	–	dBm
Minimum Output Power		–	-40	–	dBm
Offset Error Vector Magnitude		–	5	35	%
Maximum Output Power *(using Power Mode 2, Power Setting -2)*	ZICM35xSP2	–	+20	21	dBm
Minimum Output Power		–	-40	–	dBm
Offset Error Vector Magnitude		–	5	35	%
Receiver					
Sensitivity (1% PER, Boost Mode)	ZICM35xSP0	–	-100	-94	dBm
Saturation (Maximum Input Level)		0	–	–	dBm
Sensitivity (1% PER, Normal Mode)	ZICM35xSP2	–	-103	-97	dBm
Saturation (Maximum Input Level)		-10	–	–	dBm

Note: *The ZICM35xSP2, Power Mode 2 with Power Setting -2 is the maximum setting allowed for FCC Compliance. Operating in Power Mode 3 at higher power settings may damage the PA.*

PIN SIGNALS I/O PORT CONFIGURATION

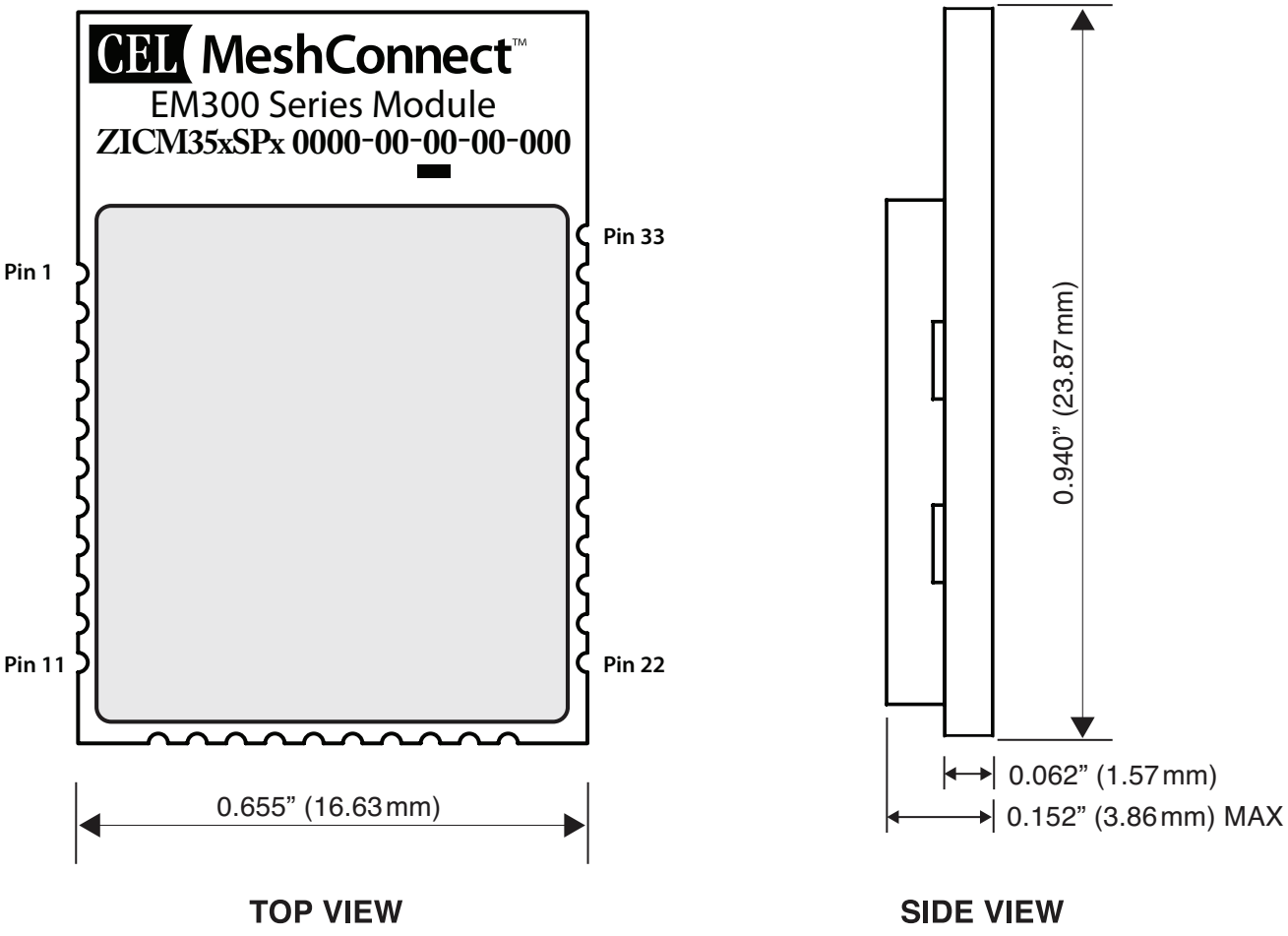
CEL's MeshConnect Module has 33 edge I/O interfaces for connection to the user's host board. See the MeshConnect Module Dimensions Section which details the layout of the 33 edge castellations.

I/O PIN ASSIGNMENTS

CEL MeshConnect ZICM35xSPx Module Pin Number	EM35x IC Pin Number	Name	Notes
1, 2, 12, 31, 33	49	GROUND	
3	11	PC5	ZICM35xSP0: Digital I/O ZICM35xSP2: Dedicated as TX_ACTIVE. The EM35x baseband controls TX_ACTIVE and drives it high when in TX mode; since it is used internally in the module, PC5 is not connected to module I/O pin 3
4	12	RESET	Active Low chip reset (Input)
5	13	PC6	ZICM35xSP0: Digital I/O ZICM35xSP2-1: Digital I/O ZICM35xSP2-2: Used internally in the module; PC6 is not connected to module I/O pin 5
6	14	PC7	Digital I/O
7	18	PA7	Digital I/O
8	19	PB3	Digital I/O
9	20	PB4	Digital I/O
10	21	PA0	Digital I/O
11	22	PA1	Digital I/O
13	16, 23, 28, 37	V_{DD}	
14	24	PA2	Digital I/O
15	25	PA3	Digital I/O
16	26	PA4	Digital I/O
17	27	PA5	Digital I/O
18	29	PA6	Digital I/O
19	30	PB1	Digital I/O
20	31	PB2	Digital I/O
21	32	JTCK	JTAG clock input from debugger
22	33	PC2	Digital I/O
23	34	PC3	Digital I/O
24	35	PC4	Digital I/O
25	36	PB0	Digital I/O
26	38	PC1	Digital I/O
27	40	PC0	Digital I/O
28	41	PB7	Digital I/O
29	42	PB6	Digital I/O
30	43	PB5	Digital I/O
32	NC	RF Out	Castellation Pin for external Antenna

MODULE DIMENSIONS

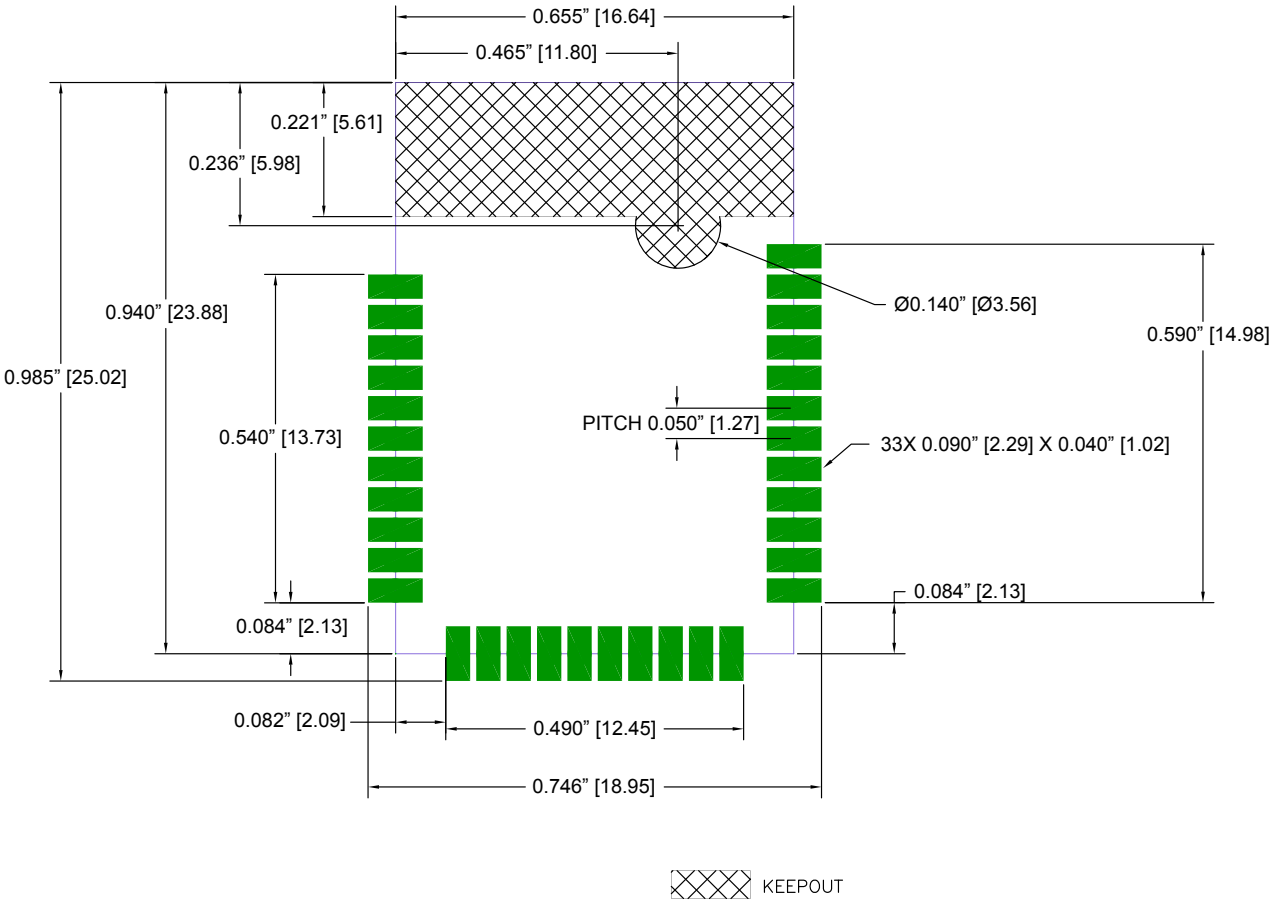
MeshConnect EM35x Mini Modules



Note: *All dimensions are +/- 0.005" (0.12 mm) unless otherwise specified.*

MODULE LAND FOOTPRINT

Dimensions are shown in inches, with millimeter conversions in brackets.



Note: *Refer to the Antenna Section in this document for layout recommendations which will yield optimal antenna performance.*

PROCESSING

Recommended Reflow Profile

Parameter Values	
Ramp Up Rate (from $T_{soakmax}$ to T_{peak})	3°/sec max
$T_{soakmin}$	150°C
$T_{soakmax}$	200°C
Soak Time	60-120 sec
$T_{Liquidus}$	217°C
Time above $T_{Liquidus}$	60-150 sec
T_{peak}	250°C
Time within 5° of T_{peak}	20-30 sec
Time from 25° to T_{peak}	8 min max
Ramp Down Rate	6°C/sec max

Pb-Free Solder Paste

Use of "No Clean" soldering paste is strongly recommended, as it does not require cleaning after the soldering process.

Note: *The quality of solder joints on the castellations ("half vias") where they contact the host board should meet the appropriate IPC Specification. See the Castellated Terminations Section in the latest IPC-A-610 Acceptability of Electronic Assemblies document.*

Cleaning

In general, cleaning the populated module is strongly discouraged. Residuals under the module cannot be easily removed with any cleaning process.

- Cleaning with water can lead to capillary effects where water is absorbed into the gap between the host board and the module. The combination of soldering flux residuals and encapsulated water could lead to short circuits between neighboring pads. Water could also damage any stickers or labels.
- Cleaning with alcohol or a similar organic solvent will likely flood soldering flux residuals into the two housings, which is not accessible for post-washing inspection. The solvent could also damage any stickers or labels.
- Ultrasonic cleaning could damage the module permanently.

The best approach is to consider using a "No Clean" solder paste and eliminate the post-soldering cleaning step.

Optical Inspection

After soldering the module to the host board, consider optical inspection to check the following:

- Proper alignment and centering of the module over the pads
- Proper solder joints on all pads
- Excessive solder or contacts to neighboring pads or vias

Repeating Reflow Soldering

Only a single reflow soldering process is encouraged for host boards.

Wave Soldering

If a wave soldering process is required on the host boards due to the presence of leaded components, only a single wave soldering process is encouraged.

Hand Soldering

Hand soldering is possible. When using a soldering iron, follow IPC recommendations (reference document *IPC-7711*).

Rework
The MeshConnect Module can be unsoldered from the host board. Use of a hot air rework tool should be programmable and the solder joint and module should not exceed the maximum peak reflow temperature of 250°C.

Caution
If temperature ramps exceed the reflow temperature profile, module and component damage may occur due to thermal shock. Avoid overheating.

Warning
Never attempt a rework on the module itself (i.e., replacing individual components); such actions will terminate warranty coverage.

Additional Grounding
Attempts to improve the module or the system grounding by soldering braids, wires or cables onto the module RF shield cover is done at the customer's own risk. The ground pins at the module perimeter should be sufficient for optimum immunity to external RF interference.

AGENCY CERTIFICATIONS

The following Part Numbers are Certified as shown below:

Part Number	Certifications	Antenna
ZICM35xSP0-1	FCC, IC, CE	PCB
ZICM35xSP2-x	FCC, IC	PCB
ZICM35xSP2-xC	FCC, IC	Nearson S181AH-2450S

FCC Compliance Statement Part 15.19, Section 7.15 of RSS-GEN

This device complies with Part 15 of the FCC Rules and with Industry Canada licence-exempt RSS Standards. Operation is subject to the following two conditions:

1. This device may not cause harmful interference, and
2. This device must accept any interference received, including interference that may cause undesired operation.

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes:

1. l'appareil ne doit pas produire de brouillage, et
2. l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Warning (Part 15.21)

Changes or modifications not expressly approved by CEL could void the user's authority to operate the equipment.

20 cm Separation Distance

To comply with FCC / IC RF exposure limits for general population/uncontrolled exposure, the antenna(s) used for this transmitter must be installed to provide a separation distance of at least 20 cm from all persons and must not be co-located or operated in conjunction with any other antenna or transmitter.

OEM Responsibility to the FCC and IC Rules and Regulations

The MeshConnect Mini Module has been certified per FCC Part 15 Rules and to Industry Canada license-exempt RSS Standards for integration into products without further testing or certification. To fulfill the FCC and IC Certification requirements, the OEM of the MeshConnect Module must ensure that the information provided on the MeshConnect label is placed on the outside of the final product. The MeshConnect Mini Module is labeled with its own FCC ID Number and IC ID Number. If the FCC ID and the IC ID are not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. The exterior label can use wording such as the following:

"Contains Transmitter Module FCC ID: W7Z-ZICM357SP0" or "Contains FCC ID: W7Z-ZICM357SP0"
"Contains Transmitter Module IC: 8254A-ZICM357SP0" or "Contains IC: 8254A-ZICM357SP0"

or

"Contains Transmitter Module FCC ID: W7Z-ZICM357SP2" or "Contains FCC ID: W7Z-ZICM357SP2"
"Contains Transmitter Module IC: 8254A-ZICM357SP2" or "Contains IC: 8254A-ZICM357SP2"

The OEM of the MeshConnect Mini Module may only use the approved antennas (PCB Trace Antenna and external antenna (part number: S181AH-2450S)) that have been certified with this module. The OEM of the MeshConnect Mini Module must test their final product configuration to comply with Unintentional Radiator Limits before declaring FCC Compliance per Part 15 of the FCC Rules.

IC Certification — Industry Canada Statement
The term "IC" before the certification/registration number only signifies that the Industry Canada technical specifications were met.

Certification IC — Déclaration d'Industrie Canada
Le terme "IC" devant le numéro de certification/d'enregistrement signifie seulement que les spécifications techniques Industrie Canada ont été respectées.

Section 14 of RSS-210
The installer of this radio equipment must ensure that the antenna is located or pointed such that it does not emit RF field in excess of Health Canada limits for the general population. Consult Safety Code 6, obtainable from Health Canada's website: http://www.hc-sc.gc.ca/ewh-semt/pubs/radiation/radio_guide-lignes_direct-eng.php

L'article 14 du CNR-210
Le programme d'installation de cet équipement radio doit s'assurer que l'antenne est située ou orientée de telle sorte qu'il ne pas émettre de champ RF au-delà des limites de Santé Canada pour la population générale. Consulter le Code de sécurité 6, disponible sur le site Web de Santé Canada: http://www.hc-sc.gc.ca/ewh-semt/pubs/radiation/radio_guide-lignes_direct-eng.php

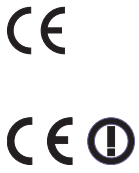
CE Certification — Europe
The MeshConnect ZICM35xSP0 Module has been tested and certified for use in the European Union.

OEM Responsibility to the European Union Compliance Rules
If the MeshConnect Module is to be incorporated into a product, the OEM must verify compliance of the final product to the European Harmonized EMC and Low-Voltage/Safety Standards. A Declaration of Conformity must be issued for each of these standards and kept on file as described in Annex II of the R&TTE Directive.

The manufacturer must maintain the user guide and adhere to the settings described in the manual for maintaining European Union Compliance. If any of the specifications are exceeded in the final product, the OEM is required to make a submission to the notified body for compliance testing.

OEM Labeling Requirements
The CE mark must be placed on the OEM product in a visible location. The CE mark shall consist of the initials CE with the following form:

- If the CE marking is reduced or enlarged, the proportions given in the CE graduated drawing (to the right) must be adhered to
- The CE mark must be a minimum of 5 mm in height
- If the use of the module is subject to restrictions in the end application, the CE marking on the OEM product should also include the alert sign as shown in the image to the right



Software Compliance

The MeshConnect Mini Modules require software restrictions to meet agency certification requirements. These restrictions have been implemented in the sample application included with the Software Development Kit.

If a customer is not starting with the CEL Software Development Kit, they must implement the following output power restrictions to use the FCC, IC or CE Certifications:

	Certification	RF Channel	Valid TX Power Steps	Typical Max Output Power
ZICM35xSP0-1	FCC/IC	11 - 25	-43 to 8	8 dBm
		26	-43 to 0	1 dBm
	ETSI	11 - 26	-43 to 8	8 dBm
ZICM35xSP2-x	FCC/IC	11 - 24	-43 to -2	20 dBm
		25	-43 to -6	17 dBm
		26	-43 to -21	-5 dBm
ZICM35xSP2-xC	FCC/IC	11 - 24	-43 to -2	20 dBm
		25	-43 to -12	9 dBm
		26	-43 to -21	-5 dBm

Note: *The ZICM35xSP2, Power Mode 2 with Power Setting -2 is the maximum setting allowed for FCC Compliance. Operating in Power Mode 3 at higher power settings may damage the PA.*

SHIPMENT, HANDLING AND STORAGE

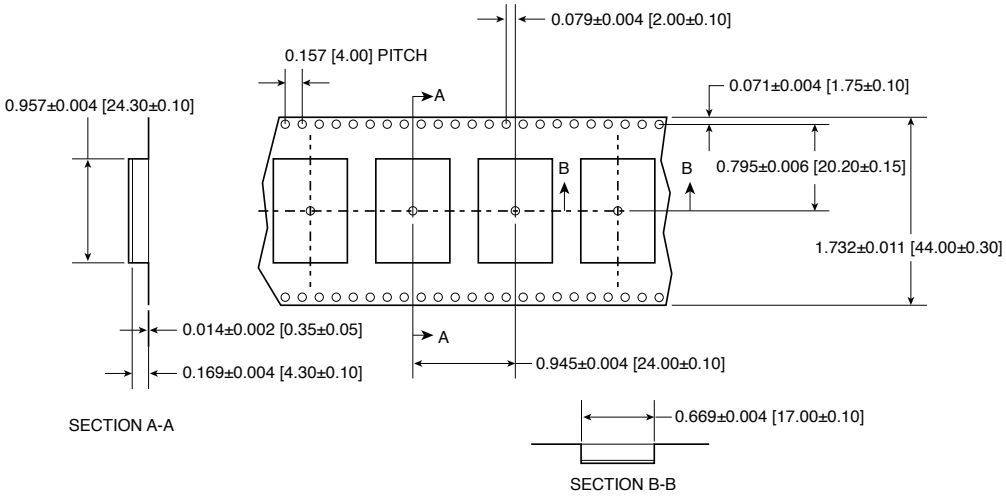
Shipment

The MeshConnect Modules have two delivery options (see Ordering Information on page 3):

1. Trays (in bundles) of 330 units. Each tray contains 66 units
2. Tape and Reel for easy assembly in a manufacturing environment. The reel diameter is 12.992 inches (330 mm) and contains 600 modules

Tape and Reel Dimensions

Measurements are in inches [mm]



Handling

The MeshConnect Modules are designed and packaged to be processed in an automated assembly line.

Warning

The MeshConnect Modules contain highly sensitive electronic circuitry. Handling without proper ESD protection may destroy or damage the module permanently.

Warning

The MeshConnect Modules are moisture-sensitive devices. Appropriate handling instructions and precautions are summarized in J-STD-033. Read carefully to prevent permanent damage due to moisture intake.

Moisture Sensitivity Level (MSL)

MSL 3, per J-STD-033

Storage

Storage/shelf life in sealed bags is 12 months at <40°C and <90% relative humidity.

QUALITY

CEL Modules offer the highest quality at competitive prices. Our modules are manufactured in compliance with the IPC-A-610 specification, Class II. Our modules go through JESD22 qualification processes which include high temperature operating life tests, mechanical shock, temperature cycling, humidity and reflow testing. CEL conducts RF and DC factory testing on 100% of all production parts.

CEL builds the quality into our products, giving our customers confidence when integrating our products into their systems.

REFERENCES

Reference Documents	Download
120-035X-000 - Silicon Labs/Ember EM35x SoC Datasheet	Link
0011-02-17-00-000 - CEL EM35x Ember Mini Module Companion Kit Technical User Guide	Link
0011-01-16-05-000 - Using the ZICM35xSPx Mini Module Programming Fixture	Link
0011-00-16-11-000 - CEL ZICM35xSP2-1C External Antenna Implementation	Link

REVISION HISTORY

Previous Versions	Changes to Current Version	Page(s)
0011-00-07-01-000 (Issue A) July 22, 2013	Initial Preliminary Datasheet	All
0011-00-07-01-000 (Issue B) August 1, 2013	Updated Development Tools Section, Antenna Section, Agency Certifications, Software Compliance Section	4, 5, 14, 16, 17
0011-00-07-01-000 (Issue C) February 10, 2014	Updated Tape and Reel Packaging	3, 17
0011-00-07-01-000 (Issue D) March 17, 2014	Updated ZICM358xSPx Sleep Mode Current. Removed "Preliminary" status for this datasheet. Updated Software Compliance "Valid" TX Power Steps" table values	1, 7, 16
0011-00-07-01-000 (Issue E) March 18, 2014	This datasheet is now a "Preliminary Datasheet" due to the addition of new part numbers (ZICM357SP2-2, ZICM357SP2-2-R, ZICM357SP2-2C and ZICM357SP2-2C-R) to the "Ordering Information". Added new "ZICM35xSPx Product Comparison Table".	1, 3

Disclaimer

The information in this document is current as of the published date. The information is subject to change without notice. For actual design-in, refer to the latest publications of CEL Data Sheets or Data Books, etc., for the most up-to-date specifications of CEL products. Not all products and/or types are available in every country. Please check with an CEL sales representative for availability and additional information.

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For More Information

For more information about CEL MeshConnect products and solutions, visit our website at: www.cel.com/MeshConnect.

Technical Assistance

For Technical Assistance, visit www.cel.com/MeshConnectHelp.

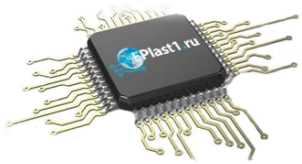
Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits,General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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